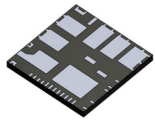


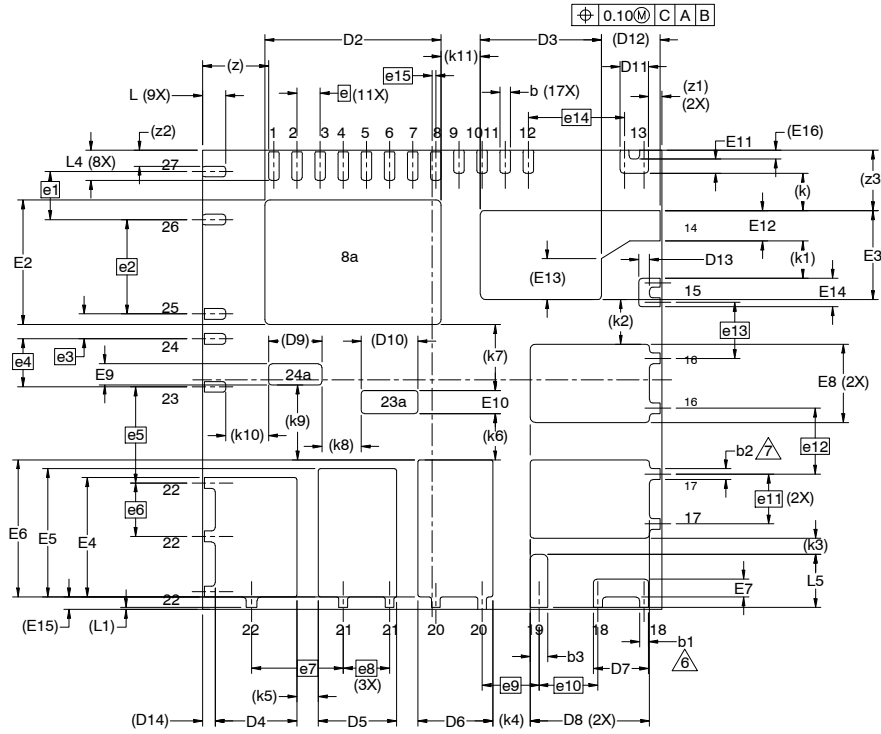
# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

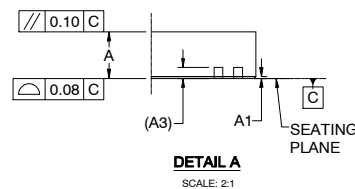


**PQFN27 12.9X12.9, 0.65P**  
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**ISSUE A**

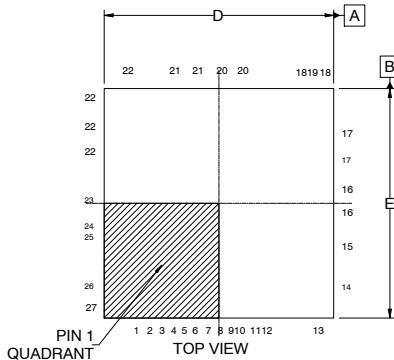
DATE 01 JUN 2021



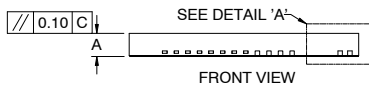
**BOTTOM VIEW**  
SCALE: 2:1



**DETAIL A**  
SCALE: 2:1



**TOP VIEW**



**FRONT VIEW**

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.20	1.30	1.40
A1	0.00	-	0.05
A3	0.25 REF		
b	0.20	0.30	0.40
b1	0.15	0.25	0.35
b2	0.20	0.30	0.40
b3	0.40	0.50	0.60
D	12.80	12.90	13.00
D2	4.85	4.95	5.05
D3	3.30	3.40	3.50
D4	2.20	2.30	2.40
D5	2.10	2.20	2.30
D6	2.00	2.10	2.20
D7	1.45	1.55	1.65
D8	3.25	3.35	3.45
D9	1.50 REF		
D10	1.60 REF		
D11	0.70	0.80	0.90
D12	1.65 REF		
D13	0.20	0.30	0.40
D14	0.35 REF		
E	12.80	12.90	13.00
E2	3.40	3.50	3.60
E3	2.40	2.50	2.60
E4	3.25	3.35	3.45
E5	3.50	3.60	3.70
E6	3.75	3.85	3.95
E7	0.40	0.50	0.60
E8	2.10	2.20	2.30
E9	0.50	0.60	0.70
E10	0.55	0.65	0.75
E11	0.30	0.40	0.50
E12	0.75	0.85	0.95
E13	1.15 REF		
E14	0.70	0.80	0.90
E15	0.35 REF		
E16	0.25 REF		

**NOTES:**

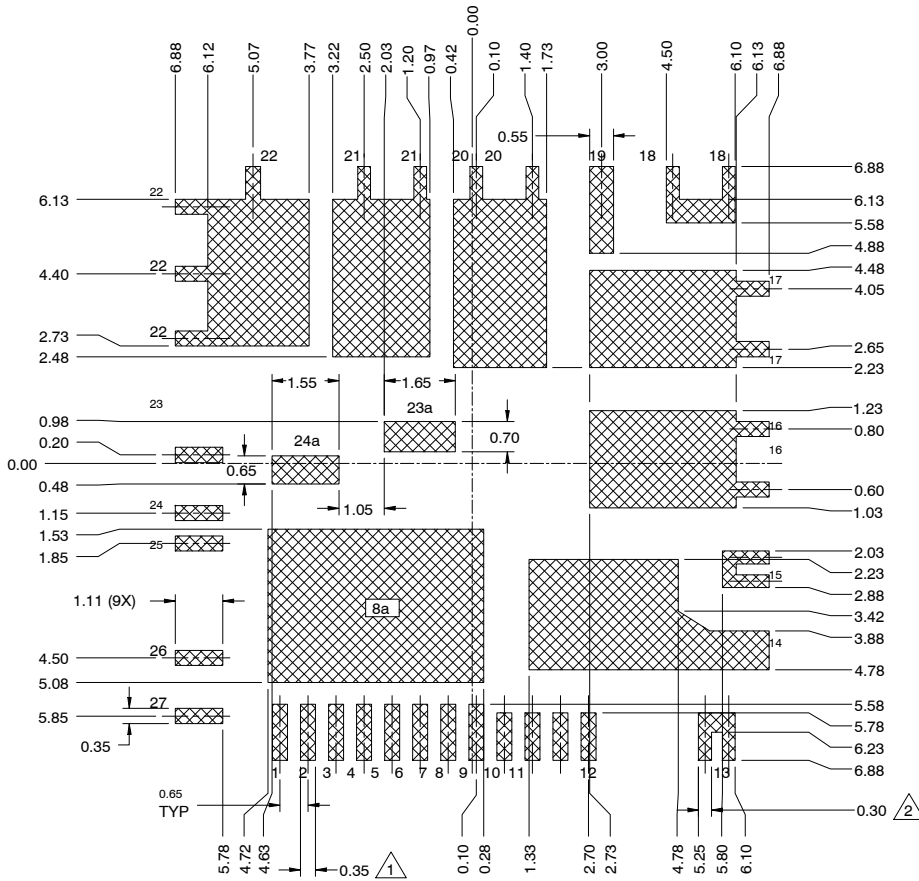
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
6. b1 IS LEAD WIDTH OF TERMINALS 13, 15, 18, 20, 21.
7. b2 IS LEAD WIDTH OF TERMINALS 16, 17, 22.

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<b>DESCRIPTION:</b>	<b>PQFN27 12.9X12.9, 0.65P</b>	<b>PAGE 1 OF 2</b>

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**ISSUE A**

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LAND PATTERN  
 RECOMMENDATION  
 SCALE: 2:1

**NOTES:**

- ① PAD WIDTH OF PINS 1-12, 16, 17, 22-27 IS 0.35MM.
- ② PAD WIDTH OF PINS 13, 15, 18, 20, 21 IS 0.30MM.

**\*FOR ADDITIONAL INFORMATION ON OUR  
 PB-FREE STRATEGY AND SOLDERING  
 DETAILS, PLEASE DOWNLOAD THE ON  
 SEMICONDUCTOR SOLDERING AND  
 MOUNTING TECHNIQUES REFERENCE  
 MANUAL, SOLDERRM/D.**

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
e	0.65 BSC		
e1	1.35 BSC		
e2	2.65 BSC		
e3	0.70 BSC		
e4	1.35 BSC		
e5	2.70 BSC		
e6	1.50 BSC		
e7	2.58 BSC		
e8	1.30 BSC		
e9	1.60 BSC		
e10	1.65 BSC		
e11	1.40 BSC		
e12	1.85 BSC		
e13	1.58 BSC		
e14	2.70 BSC		
e15	0.10 BSC		
k	1.05 REF		
k1	1.05 REF		
k2	1.25 REF		
k3	0.45 REF		
k4	1.05 REF		
k5	0.60 REF		
k6	1.30 REF		
k7	1.85 REF		
k8	1.10 REF		
k9	2.10 REF		
k10	1.20 REF		
k11	1.10 REF		
L	0.55	0.65	0.75
L1	0.05 REF		
L4	0.75	0.85	0.95
L5	1.40	1.50	1.60
z	1.85 REF		
z1	0.37 REF		
z2	0.45 REF		
z3	1.70 REF		

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